

Material Content Data Sheet

RoHS | Halogen-Free

Sales Product Name	BSC13DN30NSFD	**Issued**	08. April 2022
MA#	MA001623284		
Package	PG-TDSON-8-7	**Weight***	119.62 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	2.175	1.82	1.82	18180	18180
leadframe	inorganic material	phosphorus	7723-14-0	0.011	0.01		95	
	non noble metal	iron	7439-89-6	0.038	0.03		316	
	non noble metal	copper	7440-50-8	37.762	31.55	31.59	315677	316088
wire	noble metal	gold	7440-57-5	0.044	0.04	0.04	371	371
encapsulation	organic material	carbon black	1333-86-4	0.084	0.07		702	
	plastics	epoxy resin	-	6.637	5.55		55481	
	inorganic material	silicondioxide	60676-86-0	35.284	29.50	35.12	294963	351146
leadfinish	non noble metal	tin	7440-31-5	1.452	1.21	1.21	12135	12135
plating	noble metal	silver	7440-22-4	0.166	0.14	0.14	1384	1384
solder	non noble metal	tin	7440-31-5	0.046	0.04		387	
	noble metal	silver	7440-22-4	0.058	0.05		484	
	non noble metal	lead	7439-92-1	2.210	1.85	1.94	18473	19344
heat sink clip	inorganic material	phosphorus	7723-14-0	0.007	0.01		56	
	non noble metal	iron	7439-89-6	0.022	0.02		187	
	non noble metal	copper	7440-50-8	22.292	18.64	18.67	186353	186596
heatspreader	inorganic material	phosphorus	7723-14-0	0.003			28	
	non noble metal	iron	7439-89-6	0.011	0.01		95	
	non noble metal	copper	7440-50-8	11.320	9.46	9.47	94633	94756
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

Company	Infineon Technologies AG
Address	81726 Neubiberg
Internet	www.infineon.com